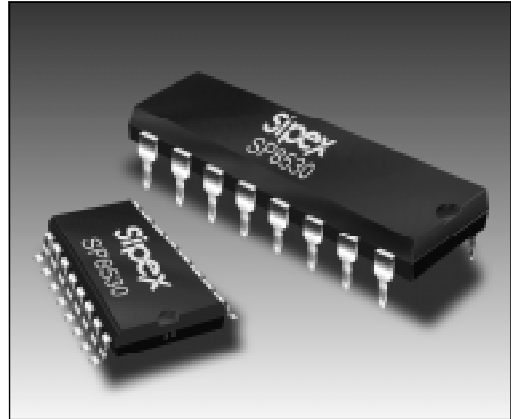


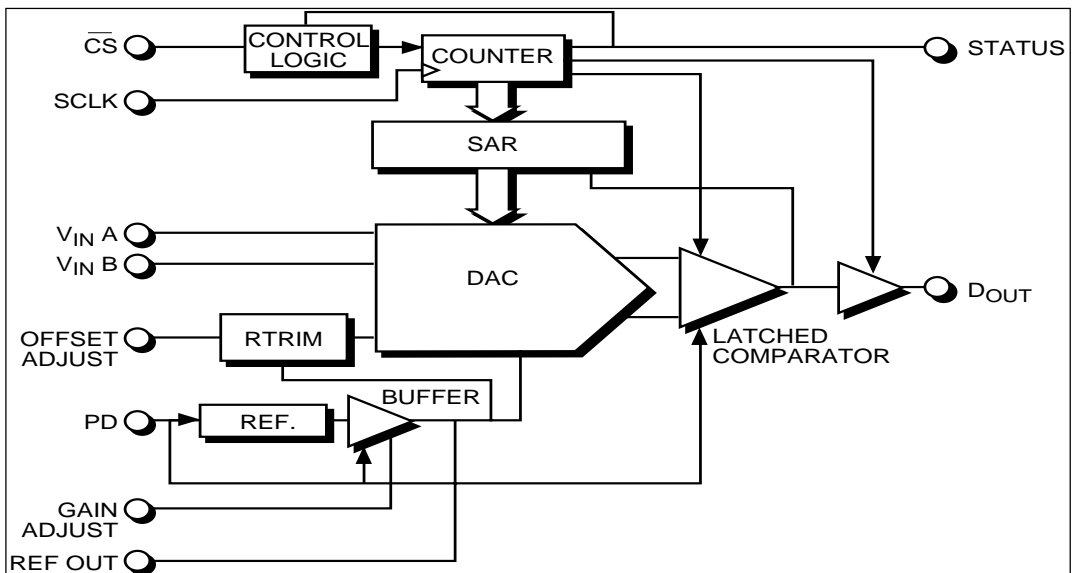
S²ADC™ - Simultaneous Sampling Analog to Digital Converter

- Patented Simultaneous Sampling of 2 channels (Patent # 5,638,072)
- 12 Bit Resolution
- Single +5Volt Supply
- Internal Reference, 1.25V
- Unipolar 0 to +2.5 Volt Input Range
- Fast, 7.75 μ s Conversion Time Both Channels
- Fast Power Shutdown/Turn-On Mode
- 3-Wire Synchronous Serial High Speed Interface
- True Differential Measurements
- 2 μ A Shutdown Mode (10 μ W)
- Low Power CMOS 60mW typical



DESCRIPTION

The **SP8530** is a two channel simultaneous sampling, 12-Bit serial out data acquisition system. The device contains a high speed 12-Bit analog to digital converter, internal reference, and sample/hold circuitry for both channels. The **8530** is available in 16-pin PDIP and SOIC packages, specified over Commercial and Industrial temperature ranges.



™-S²ADC is a TRADEMARK OF SIPEX CORPORATION Patent Pending

ABSOLUTE MAXIMUM RATINGS

(TA=+25°C unless otherwise noted)	
VDD to DGND	-0.3V to +7V
VDA to AGND	-0.3V to +7V
Vin to AGND	-0.3V to VDA +0.3V
Digital Input to VSS	-0.3V to VDD+0.3V
Digital Output to VSS	-0.3V to VDD+0.3V
Operating Temp. Range	
Commercial (J,K Version)	0°C to 70°C
Industrial (A,B Version)	-40°C to +85°C
Storage Temperature	-65°C to 150°C
Lead Temperature(Solder 10sec)	+300°C
Power Dissipation to +70°C	500mW
Derate Above 70°C	10mW/°C



CAUTION:
ESD (ElectroStatic Discharge) sensitive device. Permanent damage may occur on unconnected devices subject to high energy electrostatic fields. Unused devices must be stored in conductive foam or shunts. Personnel should be properly grounded prior to handling this device. The protective foam should be discharged to the destination socket before devices are removed.

SPECIFICATIONS

Unless otherwise noted the following specifications apply for V_{DD} = 5V with limits applicable for T_A = 25°C.

PARAMETER	MIN.	TYP.	MAX.	UNIT	CONDITIONS
DC Accuracy					
Resolution		12		Bits	
Integral Linearity					
J, A		±0.6	±1.0	LSB	
K, B		±0.4	±0.75	LSB	
Differential Linearity Error					
J, A		±0.5	±1.0	LSB	No Missing Codes
K, B		±0.5	±1.0	LSB	No Missing Codes
Gain Error					
J, A		±0.2	±1.0	%FSR	Externally Trimmable to Zero
K, B		±0.1	±0.5	%FSR	Externally Trimmable to Zero
Offset Error					
J, A		±4	±7	LSB	Externally Trimmable to Zero
K, B		±3	±5	LSB	Externally Trimmable to Zero
Gain Match					
J, A		±2		LSB	
K, B		±2		LSB	
Offset Match					
J, A		±1.0		LSB	Externally Trimmable to Zero
K, B		±0.5		LSB	Externally Trimmable to Zero
Analog Input		0 to 2.5		Volts	
Conversion Speed					
Sample Time	400			ns	
Conversion Time	7.75			µs	
Complete Cycle	8.25				
Simultaneous Convert Rate:			121	KHz	Simultaneous Pair
Clock Speed			4	MHz	
Data Rate:			242	KHz	Total Data Conversion Rate

SPECIFICATIONS (continued)

Unless otherwise noted the following specifications apply for $V_{DD} = 5V$ with limits applicable for $T_A = 25^\circ C$.

PARAMETER	MIN.	TYP.	MAX.	UNIT	CONDITIONS
Reference Output					
Ref. Out Temp. Coef. J, A K, B		1.25 15 10		Volt.Nom. ppm/ $^\circ C$ ppm/ $^\circ C$	
Ref. Out Error Output Current		± 2 1	± 25	mV mA	
Digital Inputs					
Input Low Voltage , VIL			0.8	Volt Max.	VDD=5V $\pm 5\%$
Input High Voltage , VIH	2.0			Volt Min.	VDD=5V $\pm 5\%$
Input Current IIN		± 1		μA	
Input Capacitance		3		pF Max.	
Digital Outputs					
Data Format		12-Bit Serial			See Timing diagram
Data Coding		Binary			See Timing Diagram
VOH	4.0			Volt. Min.	VDD=5V $\pm 5\%$, IOH=-0.4mA
VOL			0.4	Volt Max.	VDD=5V $\pm 5\%$, IOL=-1.6mA
AC Accuracy					
Spurious Free Dynamic Range (SFDR)		83		dB	fin=47KHz, VDD=5.0V @ 25 $^\circ C$, SCLK=4MHz
Total Harmonic Distortion (THD)		-80		dB	
Signal to Noise & Distortion (SINAD)		71		dB	
Signal to Noise (SNR)		72		dB	
Sampling Dynamics					
Acquisition Time to 0.01%		200		ns	For a $\pm FS$ step change at input
-3db Small Signal BW		13		MHz	
Aperture Delay		35		ns	
Aperture Jitter		150		ps RMS	
Aperture Delay Matching		400		ps	
Power Supplies					
VDD	4.75		5.25	Volts	

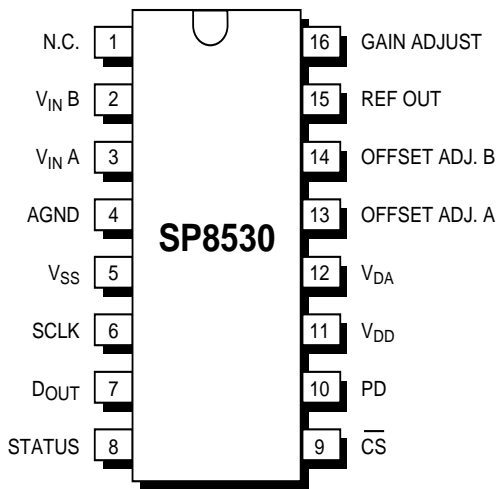
SPECIFICATIONS (continued)

Unless otherwise noted the following specifications apply for $V_{DD} = 5V$ with limits applicable for $T_A = 25^\circ C$.

PARAMETER	MIN.	TYP.	MAX.	UNIT	CONDITIONS
Power Supplies Cont.					
Supply Current Operating Mode		11.5	17	mA	SD=0, VDD=+5.0V
Shutdown Mode		0.01	2	μA	SD=1
Power Dissipation Operating Mode		60	85	mW	SD=0
Shutdown Mode		.05	10	μW	SD=1
Power Turn On			20	μS	Via Shutdown Control to 1 LSB settling error.
Temperature Range					
Commercial	0	to	+70	$^\circ C$	
Industrial	-40	to	+85	$^\circ C$	
Storage	-65	to	+150	$^\circ C$	

PIN ASSIGNMENTS

Pin 1-N.C.-No Connection
Pin 2-VIN B-Analog Input B
Pin 3-VIN A- Analog Input A
Pin 4-AGND-Analog Ground
Pin 5-VSS-Digital Ground
Pin 6-SCLK-Serial Clock Input
Pin 7-DOUT Digital Data Output
Pin 8-STATUS- High During Conversion
Pin 9-CS-Chip Select Bar Input High Deselects chip Low Selects chip
Pin 10-SD-Shutdown Input, logic low power up, logic high = powerdown
Pin 11-VDD Digital +5V supply
Pin 12-VDA Analog +5V supply
Pin 13-OffADJ-A External Offset Adjust A
Pin 14-OffADJ-B External Offset Adjust B
Pin 15-REFOUT-Voltage Reference Output
Pin 16-GAINADJ-External Gain Adjustment



FEATURES

The **SP8530** is a two channel simultaneous sampling, 12-Bit serial out data acquisition system. The device contains a high speed 12-bit analog to digital converter, internal reference, and sample and hold circuitry for both channels. The patented, simultaneous sampling feature of this monolithic integrated circuit, permits the user to measure and convert the analog information on each of two channels at the same

time, thus preserving the relevant temporal information of the applied signals, precisely. This unique feature permits the **SP8530** to ideally fit applications where the information content is carried on dual carriers, such as in-phase and quadrature phase systems. Further, S²ADC™ architecture permits the sampling of such signals without the necessity of demodulating or further conditioning of the carrier prior to conversion, potentially saving significant amounts of other support electronics. It is also suited to measure instantaneous transfer functions between input signals and their corresponding output signal.

Such measurements are commonly made in test equipment and PIN electronics as well as in many other systems where instantaneous cause and effect relationships are monitored.

The **SP8530** permits the user to convert each channel and digitally subtract the result in external logic to produce a precise digital differential result.

The **SP8530** is fabricated in Sipex' Bipolar Enhanced CMOS Process that permits state-of-the-art design using bipolar devices in the analog/linear section and extremely low power CMOS in digital/logic section.

CIRCUIT OPERATION

The operating circuit in Figure 1 shows a simple circuit required to operate the **SP8530**. The conversion is controlled by the user supplied signal Chip Select Bar (\overline{CS}) which selects and deselects the device, and a system clock (SCLK).

A high level applied to \overline{CS} asynchronously clears the internal logic, puts the sample & hold (CDAC) into sample mode and places the DOUT (Data Output) pin in a high impedance state.

Conversion is initiated by falling edge on \overline{CS} in slave mode at which point the selected input voltages are held and a conversion is started. A delay of 90ns is required between the falling edge of \overline{CS} and the first rising of SCLK.

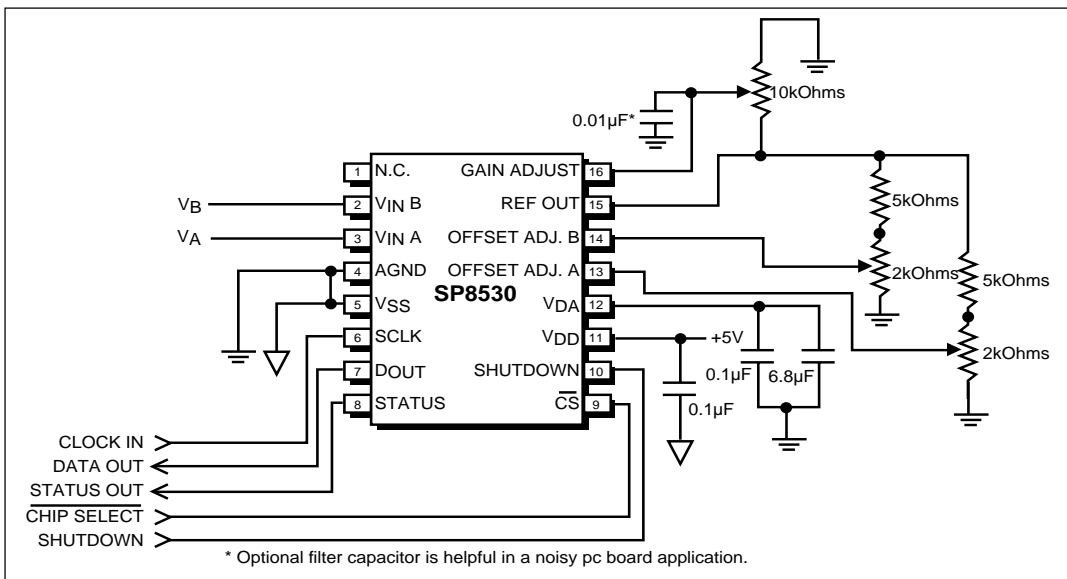


Figure 1. Operating Circuit

The device responds to the shut down signal asynchronously so that a conversion in progress will be interrupted and the resulting data will be erroneous. A 20 µSec delay is required between the falling edge of power down and initiation of a conversion.

Data Format

32 bits of data are sent for each conversion. The first 16 bits are the conversion A result, which is shipped with 4 leading "0"s, and then 12 bits of data, MSB first. The second 16 bits are the conversion B result, which are also shipped with 4 leading "0"s, and then 12 bits of data, MSB first. Data changes on the falling edge of SCLK and is stable on the rising edge of SCLK.

Continuous stand alone operation is obtained by holding \overline{CS} low. In this mode an oscillator is connected directly to SCLK pin. The SCLK signal along with the STATUS output Signal are used to synchronize the host system with the converter's data. In this mode there is a single dead SCLK cycle between the 32nd clock of one conversion and the first clock of the following conversion for the **SP8530**. A clock frequency of 4 MHz the **SP8530** provides a throughput rate of 121KHz.

In slave mode operation, \overline{CS} is brought high on each conversion so that all conversions are initiated by falling edge on \overline{CS} .

Layout Considerations

Because of the high resolution and linearity of the **SP8530** system design considerations such as ground path impedance and contact resistance become very important.

To avoid introducing distortion when driving the analog inputs of these devices, the source resistance must be very low, or constant with signal level. Note that in the operating circuit there is no connection made between VDA (Pin 12) and the system power supply. This is because the analog supply pin (VDA) is connected internally to the digital supply pin (VDD) through a ten ohm resistor.

This connection when combined with parallel combination of 6.8µF tantalum and 0.1µF ceramic capacitor between VDA and analog ground, will provide some immunity to noise which resides on the system supply. To maintain maximum system accuracy, the supply connected to the VDD pin should be well isolated from digital supplies and wide load variations.

To limit effects of digital switching elsewhere in a system, it often makes sense to run a separate +5V supply conductor from the supply regulator to any analog components requiring +5V including the **SP8530**. Noise on the power

Layout Considerations (cont.)

supply lines can degrade the converters performance, especially corrupting are noise and spikes from a switching power supply.

The ground pins (AGND and VSS) on the **SP8530** are separated internally and should be connected to each other under the converter. Applying the technique of using separate analog and digital ground planes is usually the best way to preserve dynamic performance and reduce noise coupling into sensitive converter circuits. Where any compromise must be made the common return of the analog input signal should be referenced to the AGND pin of the converter. This prevents any voltage drops that might occur in the power supply's common return from appearing in series with the input signal.

Coupling between analog and digital lines should be minimized by careful layout. For instance, if analog and digital lines must cross they should do so at right angles. Parallel analog and digital lines should be separated from each other by a trace connected to common.

If external gain and offset potentiometers are used, the potentiometers and related resistors should be located as close to the **SP8530** as possible.

Minimizing “Glitches”

Coupling of external transients into an analog to digital converter can cause errors which are difficult to debug. In addition to the above discussions on layout considerations, bypassing and grounding, there are several other useful steps that can be taken to get the best analog performance from a system using the **SP8530** converters. These potential system problem sources are particularly important to consider when developing a new system, and looking for causes of errors in breadboards.

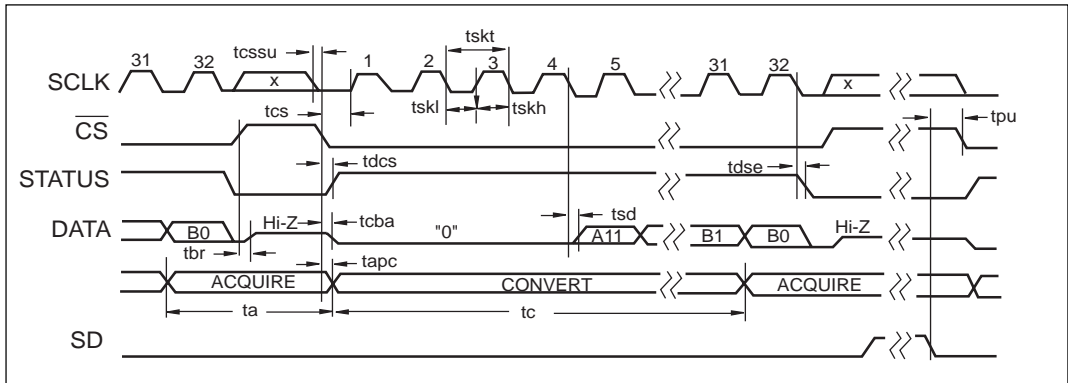
First, care should be taken to avoid transients during critical times in the sampling and conversion process. Since the **SP8530** has a internal sample/hold function, the signal that puts the device into hold state (\overline{CS} going low) is critical, as it would be on any sample/hold amplifier. The \overline{CS} falling edge should have a 5 to 10 ns transition time, low jitter, and have minimal ringing, especially during the first 20ns after it falls.

TIMING CHARACTERISTICS

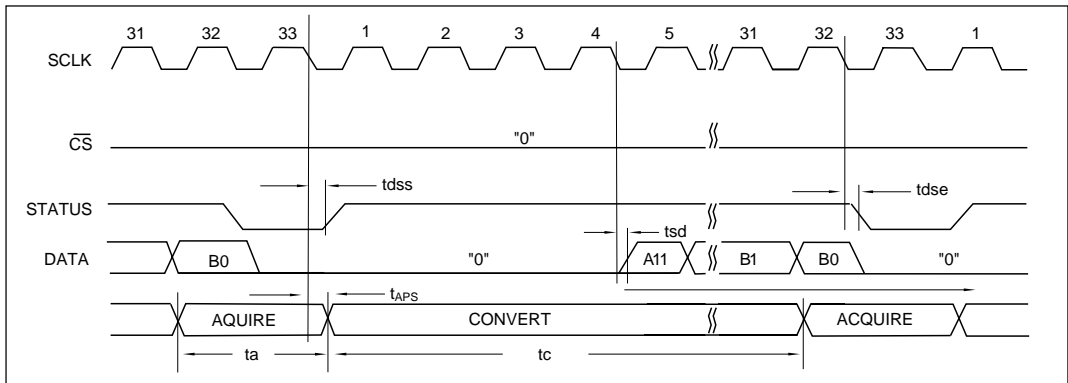
(Typical @ 25°C with $V_{DD} = +5V$, unless otherwise noted)

PARAMETER	MIN.	TYP.	MAX	UNIT	COND.
Throughput Time (tTP=tA+tC)	8.25			μs	
Acquisition Time (tA) (2 SCLK Periods)	400	500		ns	
Conversion Time (tC) (31 SCLK Periods)	7.75			μs	
SCLK Low Pulse Width (tSKL)	110	125		ns	
SCLK High Pulse Width (tSKH)	110	125		ns	
SCLK Period (tSKT)	250			ns	
Buss Access Time (tCBA)		51		ns	
Buss Relinquish Time (tBR)		45		ns	
Setup Time -SCLK Falling to CSN Falling (tCSSU)	0			ns	
CSN Low Before SCLK Rises (tCS)	90			ns	
SCLK Falling to Data Valid (tSD)		50		ns	
CSN Falling to status Rising (tDCS)		69		ns	
SCLK 33 Falling to Status Rising Free Run (tDSS)		70		ns	
SCLK32 Falling to Status Falling (tDSE)		45		ns	
Delay SD Low to initiate Conversion (tpu)		5		μs	
Aperture Delay Slave-Mode (tAPC)		30		ns	
Aperture Delay Free-Running Mode (tAPS)		35		ns	

TIMING DIAGRAMS

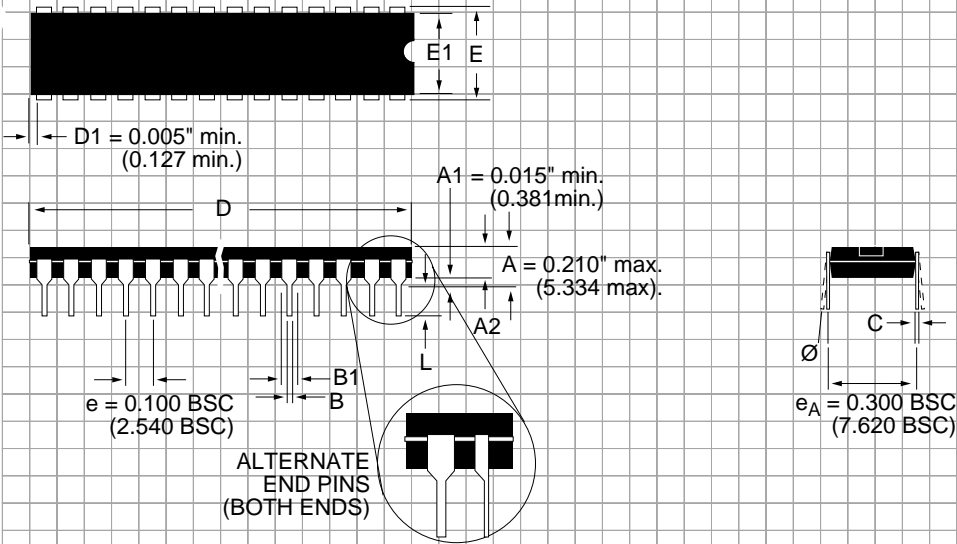


Slave Mode



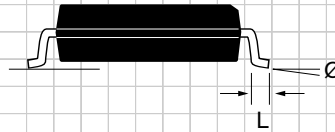
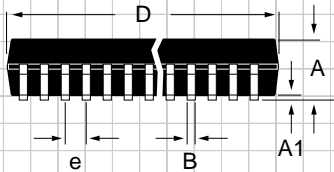
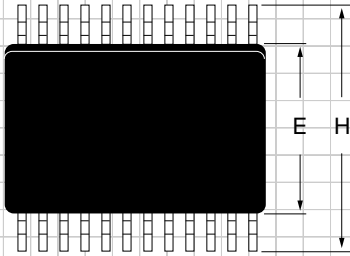
Free Running Mode

**PACKAGE: PLASTIC
DUAL-IN-LINE
(NARROW)**



DIMENSIONS (Inches) Minimum/Maximum (mm)	8-PIN	14-PIN	16-PIN	18-PIN	20-PIN	22-PIN
A2	0.115/0.195 (2.921/4.953)	0.115/0.195 (2.921/4.953)	0.115/0.195 (2.921/4.953)	0.115/0.195 (2.921/4.953)	0.115/0.195 (2.921/4.953)	0.115/0.195 (2.921/4.953)
B	0.014/0.022 (0.356/0.559)	0.014/0.022 (0.356/0.559)	0.014/0.022 (0.356/0.559)	0.014/0.022 (0.356/0.559)	0.014/0.022 (0.356/0.559)	0.014/0.022 (0.356/0.559)
B1	0.045/0.070 (1.143/1.778)	0.045/0.070 (1.143/1.778)	0.045/0.070 (1.143/1.778)	0.045/0.070 (1.143/1.778)	0.045/0.070 (1.143/1.778)	0.045/0.070 (1.143/1.778)
C	0.008/0.014 (0.203/0.356)	0.008/0.014 (0.203/0.356)	0.008/0.014 (0.203/0.356)	0.008/0.014 (0.203/0.356)	0.008/0.014 (0.203/0.356)	0.008/0.014 (0.203/0.356)
D	0.355/0.400 (9.017/10.160)	0.735/0.775 (18.669/19.685)	0.780/0.800 (19.812/20.320)	0.880/0.920 (22.352/23.368)	0.980/1.060 (24.892/26.924)	1.145/1.155 (29.083/29.337)
E	0.300/0.325 (7.620/8.255)	0.300/0.325 (7.620/8.255)	0.300/0.325 (7.620/8.255)	0.300/0.325 (7.620/8.255)	0.300/0.325 (7.620/8.255)	0.300/0.325 (7.620/8.255)
E1	0.240/0.280 (6.096/7.112)	0.240/0.280 (6.096/7.112)	0.240/0.280 (6.096/7.112)	0.240/0.280 (6.096/7.112)	0.240/0.280 (6.096/7.112)	0.240/0.280 (6.096/7.112)
L	0.115/0.150 (2.921/3.810)	0.115/0.150 (2.921/3.810)	0.115/0.150 (2.921/3.810)	0.115/0.150 (2.921/3.810)	0.115/0.150 (2.921/3.810)	0.115/0.150 (2.921/3.810)
\varnothing	0°/15° (0°/15°)	0°/15° (0°/15°)	0°/15° (0°/15°)	0°/15° (0°/15°)	0°/15° (0°/15°)	0°/15° (0°/15°)

**PACKAGE: PLASTIC
SMALL OUTLINE (SOIC)**



DIMENSIONS (Inches) Minimum/Maximum (mm)	14-PIN	16-PIN	18-PIN	20-PIN	24-PIN	28-PIN
A	0.090/0.104 (2.29/2.649)	0.090/0.104 (2.29/2.649)	0.090/0.104 (2.29/2.649)	0.090/0.104 (2.29/2.649)	0.090/0.104 (2.29/2.649)	0.090/0.104 (2.29/2.649)
A1	0.004/0.012 (0.102/0.300)	0.004/0.012 (0.102/0.300)	0.004/0.012 (0.102/0.300)	0.004/0.012 (0.102/0.300)	0.004/0.012 (0.102/0.300)	0.004/0.012 (0.102/0.300)
B	0.013/0.020 (0.330/0.508)	0.013/0.020 (0.330/0.508)	0.013/0.020 (0.330/0.508)	0.013/0.020 (0.330/0.508)	0.013/0.020 (0.330/0.508)	0.013/0.020 (0.330/0.508)
D	0.348/0.363 (8.83/9.22)	0.398/0.413 (10.10/10.49)	0.447/0.463 (11.35/11.74)	0.496/0.512 (12.60/13.00)	0.599/0.614 (15.20/15.59)	0.697/0.713 (17.70/18.09)
E	0.291/0.299 (7.402/7.600)	0.291/0.299 (7.402/7.600)	0.291/0.299 (7.402/7.600)	0.291/0.299 (7.402/7.600)	0.291/0.299 (7.402/7.600)	0.291/0.299 (7.402/7.600)
e	0.050 BSC (1.270 BSC)	0.050 BSC (1.270 BSC)	0.050 BSC (1.270 BSC)	0.050 BSC (1.270 BSC)	0.050 BSC (1.270 BSC)	0.050 BSC (1.270 BSC)
H	0.394/0.419 (10.00/10.64)	0.394/0.419 (10.00/10.64)	0.394/0.419 (10.00/10.64)	0.394/0.419 (10.00/10.64)	0.394/0.419 (10.00/10.64)	0.394/0.419 (10.00/10.64)
L	0.016/0.050 (0.406/1.270)	0.016/0.050 (0.406/1.270)	0.016/0.050 (0.406/1.270)	0.016/0.050 (0.406/1.270)	0.016/0.050 (0.406/1.270)	0.016/0.050 (0.406/1.270)
Ø	0°/8° (0°/8°)	0°/8° (0°/8°)	0°/8° (0°/8°)	0°/8° (0°/8°)	0°/8° (0°/8°)	0°/8° (0°/8°)

ORDERING INFORMATION

Model segment				
Model	INL Linearity (LSB)	Temperature Range	Package Types	
SP8530JN	±1.0	0°C to +70°C	16-pin, 0.3" Plastic DIP	
SP8530JS	±1.0	0°C to +70°C	16-pin, 0.3" SOIC	
SP8530KN	±0.75	0°C to +70°C	16-pin, 0.3" Plastic DIP	
SP8530KS	±0.75	0°C to +70°C	16-pin, 0.3" SOIC	
SP8530AN	±1.0	-40°C to +85°C	16-pin, 0.3" Plastic DIP	
SP8530AS	±1.0	-40°C to +85°C	16-pin, 0.3" SOIC	
SP8530BN	±0.75	-40°C to +85°C	16-pin, 0.3" Plastic DIP	
SP8530BS	±0.75	-40°C to +85°C	16-pin, 0.3" SOIC	

Please consult the factory for pricing and availability on a Tape-On-Reel option.



SIGNAL PROCESSING EXCELLENCE

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